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ICT Project No 871813 **MUNDFAB**

Modeling Unconventional Nanoscaled **Device FABrication**

D7.5: Symposium at the E-MRS Spring Meeting

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Quality management

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Abstract

To enable an intensive exchange of information as well as for a widest-possible dissemination of the MUNDFAB project results, a symposium on "Materials engineering for advanced semiconductor devices" ¹ (symposium M in the alphabetic list) was organized at the Spring Meeting 2023 of the European Materials Research Society (E-MRS) from May 29 to June 2, 2023, in Strasbourg, France.

1 Timing of the symposium

Originally, the symposium was planned for Spring 2022. However, in November 2020 it became clear that there was no call for symposia for the E-MRS Spring Meeting 2022. This was, because of the COVID-19 pandemic, the already defined E-MRS Spring Meeting 2021 was postponed to 2022. This left us the choice between applying for a symposium at the E-MRS Fall Meeting 2022 or the E-MRS Spring Meeting 2023. At the beginning of 2021, a symposium at the E-MRS Spring Meeting 2023 would have been five months after the formal end of MUNDFAB. However, it was already foreseeable that MUNDFAB would need to apply for an extension and there were good reasons for not applying for a symposium at the E-MRS Fall Meeting 2022: On the one hand side, topics like those of MUNDFAB have always (or traditionally) been included rather in the Spring Meetings and on the other hand also because in Fall there are several other conferences of importance in our area (ESSDERC, SISPAD, GADEST, ECSCRM and ICSCRM) which might reduce the number of potential participants. A further motivation was that the 2023 E-MRS Spring Meeting was the first one expected to be held again in person. After consultation with Prof. Peter Wellmann, at that time president of E-MRS, and Prof. Juan Ramón Morante, one of the chairs of the E-MRS Spring Meeting 2022, we have decided to apply for a symposium at the Spring Meeting 2023, even at the risk of having no other opportunity if this proposal is rejected.

Finally, after the call for symposia was published in July 2021, the proposal for our symposium was submitted by January 2022 and accepted on May 13, 2022.

2 Symposium details

To attract a broad community, "Materials engineering for advanced semiconductor devices" was chosen as title for the symposium and besides the MUNDFAB members F. Cristiano, A. Alberti and P. Pichler, Benjamin Colombeau of our Privileged Partner Applied Materials and Prof. Lourdes Pelaz of the Universidad de Valladolid were asked to act as symposium organizers.

During the symposium, the symposium assistants Chiara Rossi (Fraunhofer) from the MUNDFAB team and Mohamed Abdelrahman (CEA-Leti) provided important help in running the symposium.

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¹ https://www.european-mrs.com/materials-engineering-advanced-semiconductor-devices-emrs

2.1 Scientific Committee

To assist the organizers particularly with respect to the formulation of the topics of the symposium but also the selection of invited speakers and the selection of abstracts, a Scientific Committee was established comprising highly respected researchers in the field:

- Giuseppe Arena, STMicroelectronics Catania (Italy)
- Matthias Bauer, Mattson Technology (USA)
- Medhi Bazizi, Applied Materials (USA)
- Ray Duffy, Tyndall Research Institue Cork (Ireland)
- Jonathan England, University of Surrey, Guildford (UK)
- Anne Hemeryck, CNRS-LAAS Toulouse (France)
- Yu-Long Jiang, Fudan University Shanghai (China)
- Paweł Piotr Michałowski, Ł-IMIF Warsaw (Poland)
- Enrico Napolitani, University of Padova (Italy)
- Benoit Sklenard, CEA-LETI Grenoble (France)
- Dimitris Tsoukalas, NTUA Athens (Greece)
- Marilena Vivona, CNR-IMM Catania (Italy)

of which Anne Hemeryck, Paweł Piotr Michałowski, Enrico Napolitani, and Benoît Sklénard are members of the MUNDFAB team.

2.2 Topics

Following and extending the scope of MUNDFAB, contributions were asked for in the following fields:

- Substrate Fabrication: epitaxial growth of semiconductor materials and related compounds (Si, Ge, SiGe, SOI, SiC, GaN, ...); strained and unstrained layers; compliant substrates for heteroepitaxial growth, selective growth on patterned substrates
- Nanostructured and new materials for future devices: 2D channel materials, nanowires, nanosheets, dielectrics, materials for quantum technology
- Dopant and contact engineering: in-situ and advanced implant doping methods, silicide and germanide formation, multilevel metallization schemes (pre-cleaning, early stages of phase nucleation, interdiffusion, strain...)
- Selective and low thermal budget processes: selective dielectric deposition, localised epitaxy and etching, ultra-fast (Flash and Laser) annealing methods, radical-based surface treatments
- Surfaces and interfaces: surface passivation, structural and electrical properties of channel/dielectric and junction/metal interfaces, thin film and high-k dielectric materials...
- Metrology and characterization: new advances in the structural and electrical characterization of semiconductor materials and related compounds (nanoscale characterization, 3D, ...)
- Integration issues: 3D monolithic and heterogeneous integration, layer transfer
- Applications in advanced devices: nanoelectronic devices (FinFETs, FD-SOI, GAA-FETs, cryogenic MOS), high-bandgap power transistors (SiC MOSFETs and diodes, GaN HEMTs ...)

 Modeling and Simulations of the above listed materials' properties and processes (from ab-initio to continuum TCAD)

2.3 Invited presentations

To stimulate the submission of abstracts, and to give the symposium a certain structure, experts in the respective fields were invited to give presentations about the respective state-of-the-art:

- Laurent Brunet, CEA-Leti, Université Grenoble Alpes, France: Recent advances in 3D sequential integration
- Nadine Collaert, IMEC, Belgium: Enabling High-capacity 6G Wireless Communication: Harnessing the Potential of InP Semiconductors
- Pierre Eyben, IMEC, Belgium: Combining cutting-edge metrology techniques and TCAD to support device integration towards the 2nm Technological Node and Beyond
- Magali Gregoire, STMicroelectronics, France: Optimization of the contact engineering processes in the frame of advanced semiconductor devices development
- Antonino La Magna, CNR-IMM, Italy: Multiscale simulations of critical processes for the fabrication and functionalization of nanostructures
- Miguel A. L. Marques, Institut für Physik, Martin-Luther-Universität Halle-Wittenberg, Germany: Machine-learning-assisted determination of the global zero-temperature phase diagram of materials
- Dominique Mangelinck, IM2NP-CNRS-AMU, France: Some challenges and issues for contacts formation and stability in microelectronics
- Victor Moroz, Synopsys, USA: Material Engineering for Advanced CMOS Technology
- Michael Nolan, Tyndall National Institute, Ireland: Modelling of Interfaces and Surface reactions
- Daniele Pagano, STMicroelectronics, Italy: Virtualization of processes, metrology and maintenance for advanced SiC-based device manufacturing
- Ionut Radu, Soitec, France: New Substrate Materials for Advanced Electronic Devices
- Kentarou Sawano, Tokyo City University, Japan: Strain engineering of Si/Ge heterostructures based on Ge virtual substrates
- Werner Schustereder, Infineon Technologies Austria AG, Austria: Advanced Processes for Power Devices
- Shashank Sharma, Applied Materials, USA: Novel Processes for Advanced Nanoelectronics Devices
- André Vantomme, KU Leuven, Belgium: Tuning nickel silicide properties via ion implantation: the role of defects and impurities

2.4 Sponsors

Based on the attractive topics and with the help of many MUNDFAB team members, the following sponsors could be acquired:



The European Nanoelectronics Access Network



ASM International



LAAS/CNRS featuring also MUNDFAB



LASSE Laser System & Solutions of Europe



Mattson Technology



Calls for abstracts, abstract submissions and program

After collecting a list of email addresses of potential contributors, calls for abstracts were sent out on November 8, 2022, December 5, 2022, and January 5, 2023.

In response to the calls, the symposium received nearly 250 abstracts, which is roughly twice the number of abstracts we got for symposia at E-MRS Spring Meetings in the past but also which one typically gests for a conference like SISPAD, GADEST, or even ESSDERC. In order to select the abstracts within a relatively short time, not only the Scientific Committee but also the invited speakers were asked and helped in assessing the abstracts. The graph in Figure 1

shows the number of abstracts which have obtained a higher score than the value on the abscissa.

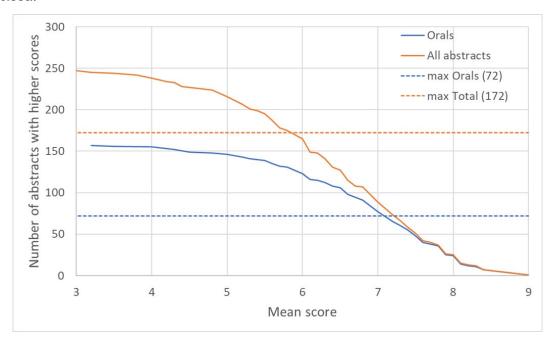


Figure 1: Abstracts with score higher than value on x-axis.

Within the limitations of the E-MRS Spring Meeting with its program from Monday morning to Friday noon, 72 contributed oral presentations and two poster sessions with 50 posters each could be accepted. The full program with the contributions from MUNDFAB members highlighted can be found by the end of the deliverable.

4 Awards

The symposium could nominate two Young Researcher Awards. The committee responsible for the selection among twelve candidates consisted of

- Jonathan England, University of Surrey, Guildford (UK)
- Peter Pichler, Fraunhofer IISB, Erlangen (Germany)
- Ionut Radu, Soitec (France)
- Werner Schustereder, Infineon Technologies Austria AG (Austria)

and dedicated the awards to

- Julien Bassaler, Univ. Grenoble Alpes, CNRS, Grenoble INP, Institut Néel, Grenoble (France) for his contribution "Investigation of electron mobility in AlGaN channel heterostructures with different Al content"
- Tadeáš Hanuš, Institut Interdisciplinaire D'innovation Technologique, Université de Sherbrooke and Laboratoire Nanotechnologies Nanosystèmes (IN2) – CNRS Irl-3463, Sherbrooke (Canada) for his contribution "Growth of transferable germanium membranes on porous substrate for flexible optoelectronics"

In addition, to encourage presenters of posters, we award four prizes for the best posters (two per session). Considering that 50 posters had to be assessed in less than two hours, two committees were established. The committee consisting of

- Enrico Napolitani, University of Padova (Italy)
- Pier Francesco Fazzini, INSA Toulouse (France)
- Antonino La Magna, CNR-IMM (Italy)

awarded the Best Poster prizes for the Tuesday poster session to

- Abdulgaffar Abdurrazaq, LAAS-CNRS, Toulouse (France) for the MUNDFAB-related contribution "Density functional theory study of multiinterstitial defects complexes in germanium"
- Ana Pérez Rodríguez, Nanotechnolgy Group, Department of Physics, University of Salamanca, Salamanca (Spain) for her contribution "Effect of gallium doping on structural and transport properties of the topological insulator Bi₂Se₃ by molecular beam epitaxy"

and the committee consisting of

- Alessandra Alberti, CNR-IMM, Catania (Italy)
- Pierre Eyben, IMEC (Belgium)
- Anne Hemeryck, CNRS-LAAS Toulouse (France)

awarded the Best Poster prizes for the Thursday poster session to

- Asmita Thool, Indian Institute of Technology, Madras Chennai (India) for her contribution "Synthesis of Large-Area Monolayer MoS₂ for Two-Terminal Neuromorphic Devices with Short-Term Memory"
- Yunchae Jeon, Yonsei University, Seoul (Korea) for her contribution "Gate/light cotunable negative differential resistance behaviors and 9 by 9 photodetectors array from small-molecules heterostructure"

5 Special issue with selected symposium contributions

To further advertise the symposium, authors of accepted abstracts were invited to contribute to a special issue on "Materials engineering for advanced semiconductor devices" in Materials Science in Semiconductor Processing with Alessandra Alberti as chief guest editor.

Following a survey, come thirty contributions can be expected for the deadline of June 30, 2023.

Conclusions

Because of the attractive scope, the symposium found an overwhelming echo in the community and offered an outstanding forum for the dissemination of MUNDFAB results but also for a plethora of discussions among colleagues who could meet again after the end of the COVID-19 pandemic.



2023 Spring Meeting May 29 | June 2 40th Anniversary

Congress & Exhibition Centre, Strasbourg, France

SYMPOSIUM M

Materials engineering for advanced semiconductor devices

Symposium Organizers:

Fuccio CRISTIANO, LAAS-CNRS, Toulouse, France

Alessandra ALBERTI, CNR-IMM, Catania, Italy

Benjamin COLOMBEAU, Applied Materials, Sunnyvale, USA

Lourdes PELAZ, Universidade de Valladolid, Spain

Peter PICHLER, Fraunhofer IISB, Erlangen, Germany

Published in Materials Science in Semiconductor Processing by Elsevier













Monday May 29

M01 Integration Challenges

Chairperson(s) : PICHLER Peter

Schuman (1st floor)

08:45	2740	INV	Recent advances in 3D sequential integration	BRUNET Laurent
09:15	958		Reconfigurable Field-Effect Transistor Technology via Heterogeneous Integration of SiGe with Crystalline Al Contacts	WIND Lukas
09:30	1411		Engineering of HZO layer for the fabrication of ultimate 3D vertical transistors for Memory-in-Logic applications	MOUSTAKAS Konstantinos
09:45	817		Isotopically Enriched 28Si Substrates for Quantum Computers Produced Using Ion Implantation Layer Exchange	ENGLAND Jonathan

Monday May 29

M02

Simulation and Modeling I

Chairperson(s): MARQUES Miguel A. L.

10:30	1974	INV	Modelling of Interfaces and Surface reactions	NOLAN Michael
11:00	1417		First Principles Calculation of Alloy Scattering Parameters and their Effect on the Mobility of GeSn	SEWELL Kevin
11:15	1551		Metal-Dielectric Adhesion Improvement Using Germanium Incorporation	BAZIZI EI Mehdi
11:30	1830		Electronic properties of interstitial atom clusters in silicon and their impact on devices	JAY Antoine
11:45	2168		Variability in Si Spin Qubits Due to Disordered Si/SiO2 Interfaces	CVITKOVICH Lukas

Monday May 29

M03

Substrate Technologies and Layer Synthesis I

Chairperson(s) : SAWANO Kentarou

Schuman (1st floor)

13:30	188	INV	New Substrate Materials for Advanced Electronic Devices	RADU Ionut
14:00	198		Low temperature epitaxial SiGe:P for gate- all-around(GAA) nMOS devices	FUJIMOTO Yuta
14:15	622		Deposition of Zr0.05Sn0.95O2 Thin Film using Mist Chemical Vapor Deposition and Its Application to Thin-Film Transistor	HSU Meng-Yu
14:30	1129		CVD-Growth of Tellurium-Based 2D Materials	GHOMI Sara
14:45	360		Direct growth of wafer-scale self-separated GaN on reusable two-dimensional material substrate	HUANG Chang-Hsun

Monday May 29

M04

Metrology and Characterization I

Chairperson(s): EYBEN Pierre

15:00	512	Raman spectroscopy in Ge and GeSn: Temperature dependence	SPIRITO Davide
15:15	1779	Polarized Raman scattering of epitaxially grown GeSn layers with different Sn contents	CORLEY-WICIAK Agnieszka Anna
15:30	526	Coupling X-ray Beam Induced Current and X-ray Diffraction Imaging to characterize diamond plates used as semiconductor-based detectors	LAFONT Fabien
15:45	1522	X-ray Nanobeam Mapping of Lattice Strain Modulations from CMOS-Processed TiN Gate Electrodes for Quantum Technologies	CORLEY-WICIAK Cedric

Monday May 29

M05 Advanced Doping Technologies

Chairperson(s) : BAUER Matthias

16:30	2509	INV	Novel Processes for Advanced Nanoelectronics Devices	SHARMA Shashank
17:00	638		Title of abstract: Study on the electrical properties of ultrathin in situ Boron-doped strained Si0.7Ge0.3 layers annealed by nanosecond pulsed laser	DAUBRIAC Richard
17:15	1027		Study on structural and electrical properties of Si:P and Si:As films treated by RTA and NLA	LEE Kihyen
17:30	1171		Sb heavy doping of Ge1-xSnx epilayers by Pulsed Laser Melting	FONTANA Daris
17:45	1308		Evolution of carrier mobility and carrier density of femtosecond laser sulfur hyperdoped silicon after different post-processing treatments	PAULUS Simon
18:00	1808		Impact of Nanosecond Laser Annealing on the Structural and Electrical Properties of Heavily in-situ B-doped SiGe Epitaxial Films	JO Chunghee
18:15	926		Phosphorus monolayers formation on Ge: towards a reliable monolayer doping	SGARBOSSA Francesco

Tuesday May 30

M06

Simulation and Modeling II

Chairperson(s): NOLAN Michael

Schuman (1st floor)

10:00	2737	INV th	Machine-learning-assisted determination of he global zero-temperature phase diagram of materials	MARQUES Miguel A. L.
10:30	1196	s	Ground and excited state properties of meta- stable allotropic forms of 2D Tellurium from irst principles approaches	GRILLO Simone
10:45	574		Charged intrinsic defect states in amorphous Si3N4	WILHELMER Christoph
11:00	710	tı	Multiscale modeling of ultrafast ransformations and structural disorder in aser annealed SiGe nanostructures	CALOGERO Gaetano
11:15	858	ir	Functionality of polycrystalline-Si channel: nsight from first-principles and multi-scale modeling	MAJI Rita
11:30	1769	F	A Multiscale Modeling Approach for Revealing Defects Relevant in Charge Trapping Related Phenomena	WALDHOER Dominic
11:45	2065	b	Kinetic Monte Carlo simulations of heated poron implantation and non-melt laser annealing in Si and SiGe layers	MUNDINAR Simon

Tuesday May 30

M07 Power Devices I

Chairperson(s): SCHUSTEREDER Werner

13:30	1508	INV	Virtualization of processes, metrology and maintenance for advanced SiC-based device manufacturing	PAGANO Daniele
14:00	1538		Growth of thick GaN layers on Si (111) for vertical power devices	MICHLER Sondre
14:15	681		Investigation of electron mobility in AlGaN channel heterostructures with different Al content	BASSALER Julien

14:30	1292		Novel Energy-Filtered Field Stop Technology for IGBT Power Devices	KOCH Robert			
14:45	932		Single step of μ s UV laser annealing for Si IGBT back-side activation	CHEHADI Zeinab			
			Tuesday May 30 M08 Silicides and Germanic Chairperson(s): MANGELINCK Domin Schuman (1st floor)				
15:00	227	INV	Optimization of the contact engineering processes in the frame of advanced semiconductor devices development.	GREGOIRE Magali			
15:30	524		Effects of roughness variation on the electrical and structural properties of Ni silicide ohmic contacts formed by UV laser annealing	BADALÀ Paolo			
15:45	2131		Investigation of the formation of nickel silicides on vertical silicon nanostructured channel for advanced electronics	MÜLLER Jonas			
Tuesday May 30 M_P01 Poster session 1 Etoile (1st floor) - 4.30 p.m to 6.30 p.m							
	01_40		Defects visualization in Gallium Nitride by Scanning Transmission Electron Microscopy	BONGIORNO Corrado			
	02_148		Investigation of carrier Lifetime variation with nanopillar spacing in Si-nanopillar/SiGe composite materials for MOSFET application by laser heterodyne photothermal displacement measurements	HARADA Tomoki			
	03_300		Deep Level Transient Spectroscopy- Secondary Ion Mass Spectrometry combined study of H+ irradiation effects on 4H-SiC	SCALISI Melissa Lucia			
	05_778		Super-Resolution Fluorescence Imaging for Semiconductor Nanoscale Metrology and Inspection	MUN Seohyun			

06_811	Band Bending and Surface Composition Analysis by Angle Resolved XPS and Their Impact on Minority Carrier Lifetime After Germanium Wet Etching	CHAPOTOT Alexandre
07_930	Manipulating spin texture in a hybrid nanostructure comprised of topological insulator and 2D semiconductor with varied band alignment types	CHENG Cheng-Maw
08_950	Thermal transport on few-layers Fe3GeTe2	CLARO Marcel S.
09_1102	Stress/strain-induced Raman frequency shift in Gallium Nitride (GaN) Packaged Devices	DAHROUCH Zainab
10_1471	Features of Ultrathin SiO2 Layers on Si and Their Physical Manifestations	KONIN Konstantin
11_1472	4H-SiC RIE etch: Design of Experiments optimization for striations recovery by using ImageJ software	BARCELLONA Matteo
12_2639	Sub-Picosecond Carrier Dynamics Explored using Automated High-Throughput Studies of Doping Inhomogeneity within a Bayesian Framework	AL-ABRI Ruqaiya
13_355	Radiation-enhanced annealing of vacancy- oxygen defects in Cz n-Si: features of the experiment, factor of the radiation ionization, and a possible annealing mechanism	KRAS'KO Mykola
14_518	New states of ??2 defect in boron-doped Si	KHIRUNENKO Lyudmila
15_627	The Diffusion Behavior and Electrical Characteristics of Ru Interconnect with Polycrystalline MoS2 Diffusion Barrier	JHAN Dun Jie
16_2411	Density functional theory study of multi- interstitial defects complexes in germanium	ABDURRAZAQ Abdulgaffar
17_2001	Gibbs free energy for MoO2Cl2 reaction on SiO2 surface by density function theory	KIM Hyun-Kyu
18_2043	Two-dimensional carrier gas at a polar interface without surface band gap states: A first principles perspective	BRIVIO Federico
19_2095	Two-dimensional van der Waals heterostructures for energy-efficient tunneling transistors	IORDANIDOU Konstantina
20_69	General Purpose Machine Learning Interatomic Potential for Silicon-Germanium	MILARDOVICH Diego
21_2050	Ab-initio study of the effects of Pb intercalation in Graphene/SiC heterostructures	BROZZESI Simone

22_1380	Tuning the Schottky Contacts of graphene/ phosphorene heterostructure: a DFT study	MURONI Alessia
23_893	TCAD modelling of a-Si:H devices for particle detection applications	PASSERI Daniele
24_1206	Post growth thermal treatments of Si1-x-yGexSny alloys	STEUER Oliver
25_43	New method for the deposition of thin films on the inner walls of a deep cavity: application to germanium doping	CARRARO Chiara
26_1476	Strained sintered mesoporous silicon epifoils for IIIV/Si integration and substrate reuse	SANCHEZ-PEREZ Clara
27_2200	Properties and perspectives of supersaturated (Si)Ge nanosheets grown via molecular beam epitaxy at ultra-low temperatures	ABERL Johannes
28_827	Impact of annealing schemes on the formation and agglomeration of thin Ni(Pt)Si film for advanced 3D imagers technologies	MORRIS ANAK Fabriziofranco
29_2081	In-situ transmission electron microscope observation of nickel metal-induced crystallization on a-Si	HSIANG Chen-Chih
30_2202	Study of interfaces in nickel-based silicides through a multi-level modeling strategy	JARA Cesar
31_189	Influence of the type of interlayer on current transport mechanisms and defects in n-ZnO/ZnCdO/p-Si and n-ZnCdO/ZnO/p-Si heterojunctions grown by molecular beam epitaxy	SZYMON Radoslaw
32_1572	Phase transition control of crystalline Ga2O3 grown on sapphire (0001) by MOCVD	KIM Hyeong-Yun
33_1915	Deposition of Ga2O3 and ZnGa2O4 thin films by liquid metal target sputtering	ZUBKINS Martins
35_805	Wafer-Scale Production of 2D SnSe: Synthetic Platform for Van der Waals Semiconductor-Based Broadband Photodetectors	JO Hyeong-Ku
36_605	Formation of High-k Al-doped ZrO2 Dielectric Using a New Cocktail Precursor	KIM Hayeong
37_1030	Effect of dopant distribution on the remanent polarization of La-doped HfO2 thin films	JEONG Ju Young
38_1019	Ferroelectricity of La doped Hf0.5Zr0.5O2 Films Deposited by Atomic Layer Deposition using Supercycles	HAN Yoogeun

39_1647	Oxygen Vacancy Control-mediated Ferroelectricity Enhancement in Hafnium Zirconium Oxide Via DUV Photoactivation	LEE Sangwoo
40_458	Chemical design of magnetoelectric GaFeO3 epitaxial thin films	NASUI Mircea
41_861	Engineering Transition Metal Oxide and Transition Metal Dichalcogenide Memristive Devices for Neuromorphic Systems	LINKENHEIL Anna
42_113	Mist-CVD Deposited c-Axis Aligned Crystalline ITZO Thin Film and Its Application to Thin-Film Transistor	LIU Han-Yin
43_1238	A comprehensive study of the influence of various deposition parameters on the physical properties of ZnO:Al thin transparent conducting films	RACZ Adel Sarolta
44_1103	High mobility Oxide Thin Film Transistor with amorphous In-Ga-Sn-O fabricated by RF-magnetron sputtering	HYUNIL Jo
45_1125	Growth Control, Optical and Structural Characterization of Layered Gallium Sulfide Films Prepared by Chemical Vapor Deposition	DICORATO Stefano
46_1992	Growth of MoSe2-MoS2 core-shell in-plane heterostructure TMDs using Chemical Vapor Deposition	LIM Insu
48_1827	Photothermal reaction based Low Temperature Synthesis of Vertically Integrated Two-dimensional Heterostructure	JEON Min-Ji
47_2454	Phase Change Sb2S3 films grown by Chemical Vapor Deposition	GIANGREGORIO Maria Michela
49_625	Manifestation of Eu dopants in Raman spectra and doping concentration profiles of {ZnCdO/ZnO} superlattices	PERLIKOWSKI Igor
50_1441	Effect of gallium doping on structural and transport properties of the Topological Insulator Bi2Se3 by molecular beam epitaxy	PÉREZ RODRÍGUEZ Ana
51_100	Extraction of single-walled carbon nanotubes of defined chirality with conjugated polymers in organic solvents	JANAS Dawid

Wednesday May 31

M09 Metrology and Characterization II

Chairperson(s): VANTOMME André

Schuman (1st floor)

10:00	2577	INV	Combining cutting-edge metrology techniques and TCAD to support device integration towards the 2nm Technological Node and Beyond	EYBEN Pierre
10:30	1933		Scanning Spreading Resistance microscopy on dopant profiles in elemental and compound semiconductors	BÖCKENDORF Tim
10:45	391		Local Strain and Alloy Composition in Ge1-xSnx Microdisks: A Study by X-ray Nanoprobe	ZOELLNER Marvin Hartwig
11:00	864		Capacitance-Voltage Measurements on SiC-Based MOS Structures: What Information Can We Get from Them?	BURENKOV Alex
11:15	1399		On the bulk photovoltaic effect in non- uniformly strained Germanium	MANGANELLI Costanza Lucia
11:30	1447		Deep multi-energy proton implantation in silicon: a SIMS study	SAMPERI Orazio
11:45	1713		Photoemission Spectroscopy on photoresist materials: A useful tool to use with caution	SAJJADIAN Faegheh

Wednesday May 31

M10 Simulation and Modeling III

Chairperson(s): LA MAGNA Antonino

13:30	2698	INV	Material Engineering for Advanced CMOS Technology	MOROZ Victor
14:00	2325		Gate-All-Around SRAM: Performance Investigation and Optimization Towards Vccmin Scaling	VYAS Pratik B
14:15	2002		Impact of solid and liquid phase reflectivity on the ultra-fast laser melting of silicongermanium alloys	RICCIARELLI Damiano

14.20	2074	Boron diffusion in germanium and the impact	KIPKF Felix
14:30	2074	of oxygen	KIPKE FEIIX
14:45	623	Generation and loss of hydrogen-boron pairs in fired silicon wafers	VORONKOV Vladimir
		Wednesday May 31	
		M11	
		Silicides and Germanic	des II
		Chairperson(s) : GREGOIRE Maga	İ
		Schuman (1st floor)	
15:00	964	Some challenges and issues for contacts formation and stability in microelectronics	MANGELINCK Dominique
15:30	1332	NiGe formation on thin Ge films by flash lamp annealing: electrical properties	REBOHLE Lars
15:45	1046	NiSi2/Si interface with segregation of one- atomic Au layer in a silicide-embeded silicon nanowires	WU Chia-Yi
		Wednesday May 31	
		M12	
		Applications in Advanced	Devices
		Chairperson(s) : ENGLAND Jonatha	
		Schuman (1st floor)	
16:30	844	Schuman (1st floor) Back-end-of-line and flexible substrate compatible ferroelectric memories for neuromorphic computing and adaptive sensing	MAJUMDAR Sayani
16:30 16:45	1029	Back-end-of-line and flexible substrate compatible ferroelectric memories for neuromorphic computing and adaptive	MAJUMDAR Sayani DE Sourav
		Back-end-of-line and flexible substrate compatible ferroelectric memories for neuromorphic computing and adaptive sensing Indium Gallium Zinc Oxide Based Ferroelectric Thin Film Transistors for Content Addressable Memory Cell	
16:45	1029	Back-end-of-line and flexible substrate compatible ferroelectric memories for neuromorphic computing and adaptive sensing Indium Gallium Zinc Oxide Based Ferroelectric Thin Film Transistors for Content Addressable Memory Cell Applications Impact of ferroelectricity on the electron-	DE Sourav

18:00	1493	New technologies for High Purity Germanium segmented detectors: from virgin crystals to innovative devices.	BERTOLDO Stefano
18:15	2484	Different Schottky barriers have been obtained by varying the Schottky metal and deposition parameters	MILAZZO Simone

Thursday June 1

M13

Substrate Technologies and Layer Synthesis II

Chairperson(s): RADU Ionut

Schuman (1st floor)

10:00	1555	INV	Strain engineering of Si/Ge heterostructures based on Ge virtual substrates	SAWANO Kentarou
10:45	920		Synthesis of MoS2 layers by sputter deposition and pulsed laser annealing.	TONON Alessandro
11:00	2166		Growth of transferable germanium membranes on porous substrate for flexible optoelectronics	HANUS Tadeas
11:15	1337		Van der Waals epitaxy of CdTe on 2D surfaces	TOURARD Enguerrand
11:30	2011		Lamellar GeP thin films: a first step on the road toward 2D-GeP	STOFFEL Mathieu
11:45	2197		Synthesis of relaxed Ge0.9Sn0.1/Ge by nanosecond pulsed laser melting	DI RUSSO Enrico

Thursday June 1

M14

Simulation and Modeling IV

Chairperson(s): HEMERYCK Anne

13:30	1168	Multiscale simulations of critical processes for the fabrication and functionalization of nanostructures	LA MAGNA Antonino
14:00	1655	Multi-Threshold Voltages Enablement Using Oxide Dipoles in WFM-Less Gate Stack for n- and p- Type GAA Devices	JADAUN Priyamvada
14:15	2089	A simulation workflow to couple the meso and atomistic scale for the CVD epitaxy of Si and SiGe-based structures	FISICARO Giuseppe
14:30	433	Accurate and efficient 3-D analytic model of ion implantation based on Legendre polynomials	ZOGRAPHOS Nikolas
14:45	1363	TCAD process simulation of self-limiting oxidation of silicon nanowires	ROSSI Chiara

Thursday June 1

M15

Silicides and Germanides III

Chairperson(s): ALBERTI Alessandra

Schuman (1st floor)

15:00	2154	INV	Tuning nickel silicide properties via ion implantation: the role of defects and impurities	VANTOMME André
15:30	898		Formation of the C54-TiSi2 phase using nanosecond laser annealing and RTA enhanced by amorphous silicon	GUELLADRESS Reda
15:45	614		Influence of the Si surface preparation on CoSi2 agglomeration	NEWMAN Andréa

Thursday June 1

M_P02 Poster session 2

Etoile (1st floor) - 4.30 p.m to 6.30 p.m

01_1404	synthesis of CsPbBr3 films on rigid and flexible substrates	SIRNA Lorenzo
02_1200	A new Combinatorial Approach for Solution Deposition of Thin Films	ZAKAY Noy
03_126	Pulsed 193 nm Excimer laser processing of 4H-SiC(0001) wafers with radiant exposure dependent "in situ" reflectivity studies for process optimization.	DELMDAHL Ralph
04_1026	Investigation of the dopant activation in ultrahighly B-doped Si1-xGex films	LEE Kiseok
05_1506	Wet etching characteristics of poly-Si depending on the various structures for advanced 3D integrated circuits	JI Sanghyeon
06_1539	Impact of Si3N4 stoichiometry on the formation of an AlN layer in an Al/Ti/Si3N4 thin film system during AlGaN/GaN Ohmic contact formation for HEMT device	COLOMBO Selene
07_1159	Neuromorphic Synapse Implementation using InOx Interfacial Layer in InAs Nano- Wire Field-Effect Transistor	LEE Junseo

08_1574	Symmetric nitride-based ambipolar transistors with tunable electrical properties by high electronegativity dopant	PARK Ji-Min
09_2488	Fabricating Cfet Devices with Vertically Stacked P/N Si Channels Using Ge/Si 2D Epitaxy and High Ge/Si Selective Etching Ratio	CHUN-LIN Chu
11_1868	Electrical properties of graphene field- effect transistor (GFET) by minority carrier resistance effect of graphene	GU Taejun
12_1865	Electrical Characteristics (80 – 525 K) of High Quality Pt SBDs Fabricated on HVPE-Grown ß-Ga2O3 Epilayers	SHEORAN Hardhyan
13_138	Reliable Multiply-Accumulate Operation of a Ru/TaOx/Si:ZrOx/TiN Stacked Device	SEO Hyun Kyu
14_149	Tailoring the multilevel resistive switching characteristics of hafnium oxide-based memory devices by differential work function engineering	S. P. Swathi
15_1626	Self-assembled Tantalum oxide/2H-TaS2 as van der Waals Platform of Multilevel Memristor Circuit with B-Ga2O3 Transistor	KIM Taewook
16_1674	Multiply-Accumulate Operation on One Selector-One Resistor(1S1R) 32 x 32 crossbar arrays	LEE Su Yeon
17_2155	Synthesis of Large-Area Monolayer MoS2 for Two-Terminal Neuromorphic Devices with Short-Term Memory	THOOL Asmita
18_2204	Transposable 1T-SRAM for neuromorphic computing	LIM Doohyeok
19_2508	Resistive switching properties of CuxO films through phase transition during low-temperature annealing	KIM Eun Kyu
20_2514	Synthesis and memristor properties of CVD grown ReS2 thin film: Change from DRAM to WORM	AGGARWAL Pallavi
21_772	Deposition of TiO2 Thin Films by Mist Chemical Vapor Deposition and Their Application to Resistive Random Access Memory	CHENG Yun-Yun
22_1007	Efficient Inverted Tandem Structure of Quantum Dot Light-Emitting Diodes with Inorganic Charge Generation Layers	LEE Kwangkeun
23_1058	Ligand exchanged highly dispersed NiO nanoparticles for hole injection layer of Quantum Dots LED	HYOJUN Lim

24_1338	Interplay between strain, Sn content and temperature in GeSn optoelectronic devices	ZAITSEV Ignatii
25_1544	Investigation of Chiral Halide Perovskite/III-V LEDs with Circularly Polarized Emission	HAUTZINGER Matthew
261921	Carrier dynamics and structural properties of hybrid orange-red LED based on In-rich InGaN/GaN multiple quantum wells	ALAMOUDI Hadeel
27_1926	Studying the carrier dynamic of pyramid- shaped InGaN/GaN micro-light-emitting diodes (µ-LEDs) by using Time-resolved photoluminescence	ALRESHIDI Fatimah
28_333	AlxZn1-xO-based Ultraviolet Photodetectors with Tunable Cutoff Wavelength from Near-UV to Deep-UV	CHEN Wei-Han
29_1250	Gate/Light Co-Tunable Negative Differential Resistance Behaviors and 9 by 9 Photodetectors Array from Small-Molecules Heterostructure	JEON Yunchae
30_1703	Effect of Sn+ ion implantation and post- annealing on enhancing ß-Ga2O3– based DUV self-powered photodetector performance	UPADHYAYA Kishor
31_1223	Photosensitive graphene field-effect transistor with porous silicon supporting layer	OLENYCH Igor
32_834	Large area 4H-SiC Schottky barrier diodes as radiation detectors	KNEZEVIC Tihomir
33_1521	Ultrafast low power room temperature H2 gas sensor based on atomically sharp nanopatterned exfoliated MoS2 flakes	AGRAWAL Abhay Vivek
34_1801	Mercury (II) Selective Probe by Thin Film Transistor Based on Supramolecular Flavin- Wrapped Single-Chirality Single-Walled Carbon Nanotube	KIM Dong Hwan
35_2554	A High-temperature stable Self-driven Broadband-photodetector based on MoS2/ GaN Heterostructure.	VASHISHTHA Pargam
36_2645	Exploring light trapping of nanopillar arrays decorated with self-aligned quasi-nanolenses using near-field optical microscopy	KUMAR Ankit
37_2674	Development of AlGaAsBi for the Next Generation of APDs	CARR Matthew
381922	Synthesis of Pb-free Ag-Bi-based double perovskites thin films for photovoltaic applications	RUIZ RAGA Sonia

40_1928	Template synthesis and experimental- theoretical study of a new type of heterostructures	DAULETBEKOVA Alma
41_1084	3D-printed metasurface structure with thermal-compressed circuit patterns for phase shifter fabrication	LEE Gyeongyeong
42_1205	Electrical Conductivity and Light Sensing based on 3D Printed Nanoporous Structures	XIA Kai
43_1373	Oxide Nanopatterning using Sequential Infiltration Synthesis – In Situ FTIR study	BISWAS Mahua
44_480	Development of nanoelectromechanical device based on complementary metal oxide semiconductor for three dimensional integrated associative memory-augmented neural networks	JUNG Sang Hyun
45_876	Effect of stress and different crystal orientations on 3C-SiC resonator	LA VIA Francesco
46_2335	Investigation of Thermal ALD deposited AlOx and HfOx bilayer films for Silicon Surface Passivation	DEVI Meenakshi
47_1889	Design rules for selective deposition of silver by condensation coefficient modulation	ABRAHAMCZYK Szymon
48_1716	Control of interfacial reaction between high TC superconductor Tl2Ba2CaCu2O8 and topological insulator Bi2Se3	CHUNG Yong-Duck
49_1023	Elucidating the effects of impurities on interfacial void formation of Cu and Sn-Ag electrodeposits	JO Yugeun

Friday June 2

M16 Power Devices II

Chairperson(s): PAGANO Daniele

Schuman (1st floor)

08:45	77	INV	Advanced Processes for Power Devices	SCHUSTEREDER Werner
09:15	342		Heteroepitaxy 3C-SiC/Si Power Devices - Key Materials Challenges	WARD Peter
09:30	2096		Defect formation in 3C-SiC grown on compliance Si substrates	BONINELLI Simona
09:45	1911		Impact of doping on the stress evaluation of Si/3C-SiC hetero-epitaxy	LA VIA Francesco

Friday June 2

M17

High-Mobility Electron Devices

Chairperson(s): BAZIZI El Mehdi

10:30	344	INV	Enabling High-capacity 6G Wireless Communication: Harnessing the Potential of InP Semiconductors	COLLAERT Nadine
11:00	610		Isolation of Bidimensional Electron Gas in AlGaN/GaN Heterojunction using C, Fe and Ar Ion Implantation	SCANDURRA Antonino
11:15	1939		Fabrication of Self-aligned Quantum Well InGaAs MOSFETs for High Frequency Applications	GARIGAPATI Navya Sri
11:30	152		Qualitative and quantitative defect analysis of high mobility InGaZnO oxide thin film transistor with polyimide insulator	KIM Min Jung
11:45	72		Mechanical Stress Confinement Effects on Microelectronics Reliability	HAQUE Aman